



## Material Content Data Sheet



<b>Sales Product Name</b>				ESD8V0R1B-02LS E6327		<b>Issued</b>		29. August 2013	
<b>MA#</b>				MA000866712					
<b>Package</b>				PG-TSSLP-2-1		<b>Weight*</b>		0.15 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.017	11.09	11.09	110884	110884	
leadframe	non noble metal	nickel	7440-02-0	0.036	24.43	24.43	244305	244305	
wire	noble metal	gold	7440-57-5	0.003	1.86	1.86	18554	18555	
encapsulation	organic material	carbon black	1333-86-4	0.001	0.55		5488		
	plastics	epoxy resin	-	0.011	7.41		74070		
	inorganic material	silicondioxide	60676-86-0	0.070	46.90	54.86	469109	548667	
leadfinish	noble metal	gold	7440-57-5	0.004	2.76	2.76	27630	27630	
plating	noble metal	silver	7440-22-4	0.007	5.00	5.00	49960	49960	
*deviation	< 10%			Sum in total:		100,00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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